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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	24576
Total RAM Bits	147456
Number of I/O	177
Number of Gates	1000000
Voltage - Supply	1.14V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/agl1000v2-fgg256t

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 2-20 • Different Components Contributing to the Static Power Consumption in IGLOO Devices For IGLOO V2 or V5 Devices, 1.5 V DC Core Supply Voltage

				Device-	Specific S	tatic Powe	er (mW)		
Parameter	Definition	AGL1000	AGL600	AGL400	AGL250	AGL125	AGL060	AGL030	AGL015
PDC1	Array static power in Active mode			See	Table 2-12	on page 2	2-9.		
PDC2	Array static power in Static (Idle) mode			See	Table 2-11	on page 2	2-8.		
PDC3	Array static power in Flash*Freeze mode			See	e Table 2-9	on page 2	-7.		
PDC4	Static PLL contribution				1.8	34			
PDC5	Bank quiescent power (V _{CCI} -dependent)			See	Table 2-12	2 on page 2	2-9.		
PDC6	I/O input pin static power (standard-dependent)		See Table	2-13 on pa	ge 2-10 th	rough Table	e 2-15 on p	age 2-11.	
PDC7	I/O output pin static power (standard-dependent)		See Table	2-16 on pa	ge 2-11 thr	rough Table	e 2-18 on p	age 2-12.	

Note: *For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or SmartPower tool in Libero SoC.

Combinatorial Cells Contribution—P_{C-CELL}

$$P_{C-CELL} = N_{C-CELL} * \alpha_1 / 2 * P_{AC7} * F_{CLK}$$

N_{C-CELL} is the number of VersaTiles used as combinatorial modules in the design.

 α_1 is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-23 on page 2-19.

F_{CLK} is the global clock signal frequency.

Routing Net Contribution—P_{NET}

$$P_{NET} = (N_{S-CELL} + N_{C-CELL}) * \alpha_1 / 2 * P_{AC8} * F_{CLK}$$

N_{S-CELL} is the number of VersaTiles used as sequential modules in the design.

N_{C-CELL} is the number of VersaTiles used as combinatorial modules in the design.

 α_{1} is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-23 on page 2-19.

F_{CLK} is the global clock signal frequency.

I/O Input Buffer Contribution—PINPUTS

$$P_{INPUTS} = N_{INPUTS} * \alpha_2 / 2 * P_{AC9} * F_{CLK}$$

N_{INPLITS} is the number of I/O input buffers used in the design.

 α_2 is the I/O buffer toggle rate—guidelines are provided in Table 2-23 on page 2-19.

F_{CLK} is the global clock signal frequency.

I/O Output Buffer Contribution—POUTPUTS

$$P_{OUTPUTS} = N_{OUTPUTS} * \alpha_2 / 2 * \beta_1 * P_{AC10} * F_{CLK}$$

N_{OUTPUTS} is the number of I/O output buffers used in the design.

 α_2 is the I/O buffer toggle rate—guidelines are provided in Table 2-23 on page 2-19.

 β_1 is the I/O buffer enable rate—guidelines are provided in Table 2-24 on page 2-19.

F_{CLK} is the global clock signal frequency.

RAM Contribution—P_{MEMORY}

$$P_{MEMORY} = P_{AC11} * N_{BLOCKS} * F_{READ-CLOCK} * \beta_2 + P_{AC12} * N_{BLOCK} * F_{WRITE-CLOCK} * \beta_3$$

N_{BLOCKS} is the number of RAM blocks used in the design.

F_{READ-CLOCK} is the memory read clock frequency.

 β_2 is the RAM enable rate for read operations.

F_{WRITE-CLOCK} is the memory write clock frequency.

 β_3 is the RAM enable rate for write operations—guidelines are provided in Table 2-24 on page 2-19.

PLL Contribution—PPLI

F_{CLKOUT} is the output clock frequency.[†]

[†] If a PLL is used to generate more than one output clock, include each output clock in the formula by adding its corresponding contribution (P_{AC13}* F_{CLKOUT} product) to the total PLL contribution.

Table 2-75 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.7

Applicable to Standard Plus Banks

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{zHS}	Units
100 μΑ	2 mA	Std.	1.55	6.69	0.26	1.32	1.10	6.69	5.73	3.41	3.72	12.48	11.52	ns
100 μΑ	4 mA	Std.	1.55	6.69	0.26	1.32	1.10	6.69	5.73	3.41	3.72	12.48	11.52	ns
100 μΑ	6 mA	Std.	1.55	5.58	0.26	1.32	1.10	5.58	5.01	3.77	4.35	11.36	10.79	ns
100 μΑ	8 mA	Std.	1.55	5.58	0.26	1.32	1.10	5.58	5.01	3.77	4.35	11.36	10.79	ns
100 μΑ	12 mA	Std.	1.55	4.82	0.26	1.32	1.10	4.82	4.44	4.02	4.76	10.61	10.23	ns
100 μΑ	16 mA	Std.	1.55	4.82	0.26	1.32	1.10	4.82	4.44	4.02	4.76	10.61	10.23	ns

Notes:

- 1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 μA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Table 2-76 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.2 V DC Core Voltage Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.7 Applicable to Standard Plus Banks

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{zHS}	Units
100 µA	2 mA	Std.	1.55	4.10	0.26	1.32	1.10	4.10	3.30	3.40	3.92	9.89	9.09	ns
100 µA	4 mA	Std.	1.55	4.10	0.26	1.32	1.10	4.10	3.30	3.40	3.92	9.89	9.09	ns
100 µA	6 mA	Std.	1.55	3.51	0.26	1.32	1.10	3.51	2.79	3.76	4.56	9.30	8.57	ns
100 µA	8 mA	Std.	1.55	3.51	0.26	1.32	1.10	3.51	2.79	3.76	4.56	9.30	8.57	ns
100 μΑ	12 mA	Std.	1.55	3.20	0.26	1.32	1.10	3.20	2.52	4.01	4.97	8.99	8.31	ns
100 µA	16 mA	Std.	1.55	3.20	0.26	1.32	1.10	3.20	2.52	4.01	4.97	8.99	8.31	ns

Notes:

- The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 μA. Drive strengths
 displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.
- 3. Software default selection highlighted in gray.

Table 2-107 • 1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V

Applicable to Standard Plus Banks

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
2 mA	Std.	1.55	6.32	0.26	1.11	1.10	6.43	5.81	2.47	2.16	12.22	11.60	ns
4 mA	Std.	1.55	5.27	0.26	1.11	1.10	5.35	5.01	2.78	2.92	11.14	10.79	ns
6 mA	Std.	1.55	4.56	0.26	1.11	1.10	4.64	4.44	3.00	3.30	10.42	10.22	ns
8 mA	Std.	1.55	4.56	0.26	1.11	1.10	4.64	4.44	3.00	3.30	10.42	10.22	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-108 • 1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V

Applicable to Standard Plus Banks

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
2 mA	Std.	1.55	3.22	0.26	1.11	1.10	3.26	3.18	2.47	2.20	9.05	8.97	ns
4 mA	Std.	1.55	2.72	0.26	1.11	1.10	2.75	2.50	2.78	3.01	8.54	8.29	ns
6 mA	Std.	1.55	2.43	0.26	1.11	1.10	2.47	2.16	2.99	3.39	8.25	7.94	ns
8 mA	Std.	1.55	2.43	0.26	1.11	1.10	2.47	2.16	2.99	3.39	8.25	7.94	ns

Notes:

- 1. Software default selection highlighted in gray.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-109 • 1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V

Applicable to Standard Banks

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	Std.	1.55	6.13	0.26	1.08	1.10	6.24	5.79	2.08	1.78	ns
4 mA	Std.	1.55	5.17	0.26	1.08	1.10	5.26	4.98	2.38	2.54	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-110 • 1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V

Applicable to Standard Banks

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	Std.	3.06	0.26	1.08	1.10	3.10	3.01	2.08	1.83	3.06	ns
4 mA	Std.	2.60	0.26	1.08	1.10	2.64	2.33	2.38	2.62	2.60	ns

Notes:

- 1. Software default selection highlighted in gray.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

1.2 V LVCMOS (JESD8-12A)

Low-Voltage CMOS for 1.2 V complies with the LVCMOS standard JESD8-12A for general purpose 1.2 V applications. It uses a 1.2 V input buffer and a push-pull output buffer. Furthermore, all LVCMOS 1.2 V software macros comply with LVCMOS 1.2 V wide range as specified in the JESD8-12A specification.

Table 2-127 • Minimum and Maximum DC Input and Output Levels
Applicable to Advanced I/O Banks

1.2 V LVCMOS		VIL	VIH		VOL	VOH	IOL	ЮН	IOSH	IOSL	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μ Α ⁴	μ Α ⁴
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.26	0.25 * VCCI	0.75 * VCCI	2	2	20	26	10	10

Notes:

- 1. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 2. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges
- 3. Currents are measured at 100°C junction temperature and maximum voltage.
- 4. Currents are measured at 85°C junction temperature.
- 5. Software default selection highlighted in gray.

Table 2-128 • Minimum and Maximum DC Input and Output Levels
Applicable to Standard Plus I/O Banks

1.2 V LVCMOS		VIL	VIH		VOL	VOH	I _{OL}	ЮН	IOSH	IOSL	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μ Α ⁴	μ Α ⁴
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.26	0.25 * VCCI	0.75 * VCCI	2	2	20	26	10	10

Notes:

- 1. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 2. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges
- 3. Currents are measured at 100°C junction temperature and maximum voltage.
- 4. Currents are measured at 85°C junction temperature.
- 5. Software default selection highlighted in gray.

Table 2-129 • Minimum and Maximum DC Input and Output Levels
Applicable to Standard I/O Banks

1.2 V LVCMOS		VIL	VIH		VOL	VOH	IOL	ЮН	IOSH	IOSL	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μ Α ⁴	μA ⁴
1 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	1	1	20	26	10	10

Notes:

- 1. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 2. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges
- 3. Currents are measured at 100°C junction temperature and maximum voltage.
- 4. Currents are measured at 85°C junction temperature.
- 5. Software default selection highlighted in gray.

Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

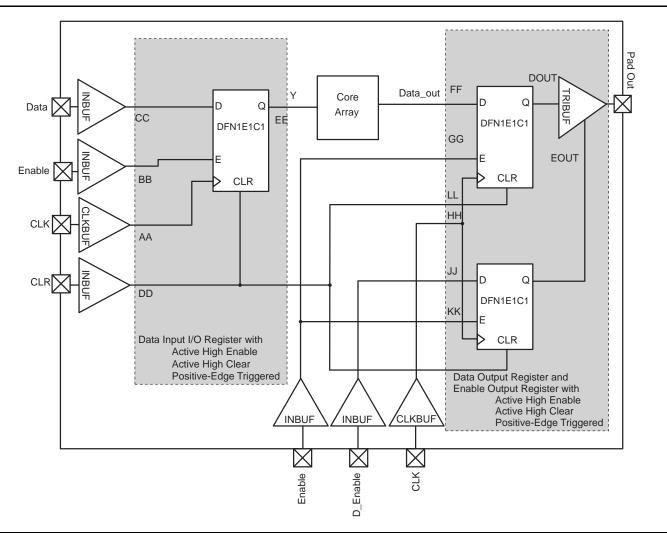


Figure 2-17 • Timing Model of the Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

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Table 2-175 • AGL060 Global Resource

Commercial-Case Conditions: T_J = 70°C, VCC = 1.425 V

			S	td.	
Parameter	Description	-	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock		1.33	1.55	ns
t _{RCKH}	Input High Delay for Global Clock		1.35	1.62	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock		1.18		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock		1.15		ns
t _{RCKSW}	Maximum Skew for Global Clock			0.27	ns

Notes:

- 1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Table 2-176 • AGL125 Global Resource

Commercial-Case Conditions: T_J = 70°C, VCC = 1.425 V

			Std.		
Parameter	Description	•	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock		1.36	1.71	ns
t _{RCKH}	Input High Delay for Global Clock		1.39	1.82	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock		1.18		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock		1.15		ns
t _{RCKSW}	Maximum Skew for Global Clock			0.43	ns

Notes:

- 1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Table 2-187 • AGL600 Global Resource

Commercial-Case Conditions: T_J = 70°C, VCC = 1.14 V

		Std.		
Parameter	Description	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock	2.22	2.67	ns
t _{RCKH}	Input High Delay for Global Clock	2.32	2.93	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock	1.40		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock	1.65		ns
t _{RCKSW}	Maximum Skew for Global Clock		0.61	ns

Notes:

- Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Table 2-188 • AGL1000 Global Resource

Commercial-Case Conditions: T_J = 70°C, VCC = 1.14 V

		Std.		
Parameter	Description	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock	2.31	2.76	ns
t _{RCKH}	Input High Delay for Global Clock	2.42	3.03	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock	1.40		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock	1.65		ns
t _{RCKSW}	Maximum Skew for Global Clock		0.61	ns

Notes:

- 1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

VJTAG JTAG Supply Voltage

Low power flash devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND. It should be noted that VCC is required to be powered for JTAG operation; VJTAG alone is insufficient. If a device is in a JTAG chain of interconnected boards, the board containing the device can be powered down, provided both VJTAG and VCC to the part remain powered; otherwise, JTAG signals will not be able to transition the device, even in bypass mode.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

VPUMP Programming Supply Voltage

IGLOO devices support single-voltage ISP of the configuration flash and FlashROM. For programming, VPUMP should be 3.3 V nominal. During normal device operation, VPUMP can be left floating or can be tied (pulled up) to any voltage between 0 V and the VPUMP maximum. Programming power supply voltage (VPUMP) range is listed in the datasheet.

When the VPUMP pin is tied to ground, it will shut off the charge pump circuitry, resulting in no sources of oscillation from the charge pump circuitry.

For proper programming, $0.01~\mu F$ and $0.33~\mu F$ capacitors (both rated at 16 V) are to be connected in parallel across VPUMP and GND, and positioned as close to the FPGA pins as possible.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

User Pins

I/O User Input/Output

The I/O pin functions as an input, output, tristate, or bidirectional buffer. Input and output signal levels are compatible with the I/O standard selected.

During programming, I/Os become tristated and weakly pulled up to VCCI. With VCCI, VMV, and VCC supplies continuously powered up, when the device transitions from programming to operating mode, the I/Os are instantly configured to the desired user configuration.

Unused I/Os are configured as follows:

- Output buffer is disabled (with tristate value of high impedance)
- Input buffer is disabled (with tristate value of high impedance)
- Weak pull-up is programmed

GL Globals

GL I/Os have access to certain clock conditioning circuitry (and the PLL) and/or have direct access to the global network (spines). Additionally, the global I/Os can be used as regular I/Os, since they have identical capabilities. Unused GL pins are configured as inputs with pull-up resistors.

See more detailed descriptions of global I/O connectivity in the "Clock Conditioning Circuits in Low Power Flash Devices and Mixed Signal FPGAs" chapter of the IGLOO FPGA Fabric User Guide. All inputs labeled GC/GF are direct inputs into the quadrant clocks. For example, if GAA0 is used for an input, GAA1 and GAA2 are no longer available for input to the quadrant globals. All inputs labeled GC/GF are direct inputs into the chip-level globals, and the rest are connected to the quadrant globals. The inputs to the global network are multiplexed, and only one input can be used as a global input.

Refer to the "I/O Structures in IGLOO and ProASIC3 Devices" chapter of the IGLOO FPGA Fabric User Guide for an explanation of the naming of global pins.

FF Flash*Freeze Mode Activation Pin

Flash*Freeze mode is available on IGLOO devices. The FF pin is a dedicated input pin used to enter and exit Flash*Freeze mode. The FF pin is active low, has the same characteristics as a single-ended I/O, and must meet the maximum rise and fall times. When Flash*Freeze mode is not used in the design, the FF pin is available as a regular I/O.

When Flash*Freeze mode is used, the FF pin must not be left floating to avoid accidentally entering Flash*Freeze mode. While in Flash*Freeze mode, the Flash*Freeze pin should be constantly asserted.

JTAG Pins

IGLOO devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). VCC must also be powered for the JTAG state machine to operate, even if the device is in bypass mode; VJTAG alone is insufficient. Both VJTAG and VCC to the part must be supplied to allow JTAG signals to transition the device. Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND.

TCK Test Clock

Test clock input for JTAG boundary scan, ISP, and UJTAG. The TCK pin does not have an internal pull-up/-down resistor. If JTAG is not used, Microsemi recommends tying off TCK to GND through a resistor placed close to the FPGA pin. This prevents JTAG operation in case TMS enters an undesired state.

Note that to operate at all VJTAG voltages, 500 Ω to 1 k Ω will satisfy the requirements. Refer to Table 3-2 for more information.

Table 3-2 • Recommended Tie-Off Values for the TCK and TRST Pins

VJTAG	Tie-Off Resistance 1,2
VJTAG at 3.3 V	200 Ω to 1 kΩ
VJTAG at 2.5 V	200 Ω to 1 kΩ
VJTAG at 1.8 V	500 Ω to 1 kΩ
VJTAG at 1.5 V	500 Ω to 1 kΩ

Notes:

- 1. The TCK pin can be pulled-up or pulled-down.
- 2. The TRST pin is pulled-down.
- 3. Equivalent parallel resistance if more than one device is on the JTAG chain

Table 3-3 • TRST and TCK Pull-Down Recommendations

VJTAG	Tie-Off Resistance*
VJTAG at 3.3 V	200 Ω to 1 kΩ
VJTAG at 2.5 V	200 Ω to 1 kΩ
VJTAG at 1.8 V	500 Ω to 1 kΩ
VJTAG at 1.5 V	500 Ω to 1 kΩ

Note: Equivalent parallel resistance if more than one device is on the JTAG chain

TDI Test Data Input

Serial input for JTAG boundary scan, ISP, and UJTAG usage. There is an internal weak pull-up resistor on the TDI pin.

TDO Test Data Output

Serial output for JTAG boundary scan, ISP, and UJTAG usage.

TMS Test Mode Select

The TMS pin controls the use of the IEEE 1532 boundary scan pins (TCK, TDI, TDO, TRST). There is an internal weak pull-up resistor on the TMS pin.

TRST Boundary Scan Reset Pin

The TRST pin functions as an active-low input to asynchronously initialize (or reset) the boundary scan circuitry. There is an internal weak pull-up resistor on the TRST pin. If JTAG is not used, an external pull-down resistor could be included to ensure the test access port (TAP) is held in reset mode. The resistor values must be chosen from Table 3-2 and must satisfy the parallel resistance value requirement. The values in Table 3-2 correspond to the resistor recommended when a single device is used, and the equivalent parallel resistor when multiple devices are connected via a JTAG chain.

In critical applications, an upset in the JTAG circuit could allow entrance to an undesired JTAG state. In such cases, Microsemi recommends tying off TRST to GND through a resistor placed close to the FPGA pin.



CS196			
Pin Number AGL400 Function			
A1	GND		
A2	GAA0/IO00RSB0		
A3	GAC0/IO04RSB0		
A4	GAC1/IO05RSB0		
A5	IO14RSB0		
A6	IO18RSB0		
A7	IO26RSB0		
A8	IO29RSB0		
A9	IO36RSB0		
A10	GBC0/IO54RSB0		
A11	GBB0/IO56RSB0		
A12	GBB1/IO57RSB0		
A13	GBA1/IO59RSB0		
A14	GND		
B1	VCCIB3		
B2	VMV0		
B2	VMV0		
В3	GAA1/IO01RSB0		
B4	GAB1/IO03RSB0		
B5	GND		
B6	IO17RSB0		
B7	IO25RSB0		
B8	IO34RSB0		
B9	IO39RSB0		
B10	GND		
B11	GBC1/IO55RSB0		
B12	GBA0/IO58RSB0		
B13	GBA2/IO60PPB1		
B14	GBB2/IO61PDB1		
C1	GAC2/IO153UDB3		
C2	GAB2/IO154UDB3		
C3	GNDQ		
C4	VCCIB0		
C5	GAB0/IO02RSB0		
C6	IO15RSB0		
C7	VCCIB0		

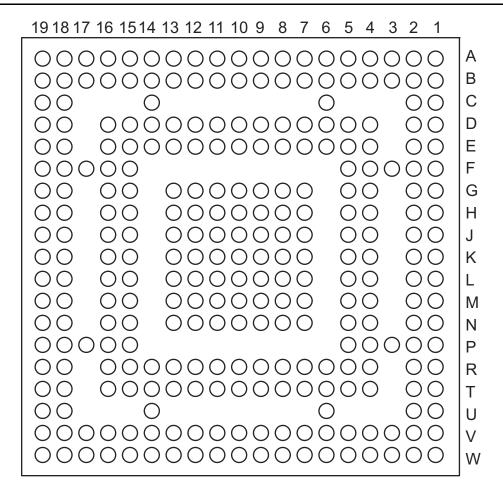
CS196				
Pin Number	AGL400 Function			
C8	IO31RSB0			
C9	IO44RSB0			
C10	IO49RSB0			
C11	VCCIB0			
C12	IO60NPB1			
C13	GNDQ			
C14	IO61NDB1			
D1	IO153VDB3			
D2	IO154VDB3			
D3	GAA2/IO155UDB3			
D4	IO150PPB3			
D5	IO11RSB0			
D6	IO20RSB0			
D7	IO23RSB0			
D8	IO28RSB0			
D9	IO41RSB0			
D10	IO47RSB0			
D11	IO63PPB1			
D12	VMV1			
D13	IO62NDB1			
D14	GBC2/IO62PDB1			
E1	IO149PDB3			
E2	GND			
E3	IO155VDB3			
E4	VCCIB3			
E5	IO151USB3			
E6	IO09RSB0			
E7	IO12RSB0			
E8	IO32RSB0			
E9	IO46RSB0			
E10	IO51RSB0			
E11	VCCIB1			
E12	IO63NPB1			
E13	GND			
E14	IO64PDB1			
F1	IO149NDB3			

CS196				
Pin Number	AGL400 Function			
F2	IO144NPB3			
F3	IO148PDB3			
F4	IO148NDB3			
F5	IO150NPB3			
F6	IO07RSB0			
F7	VCC			
F8	VCC			
F9	IO43RSB0			
F10	IO73PDB1			
F11	IO73NDB1			
F12	IO66NDB1			
F13	IO66PDB1			
F14	IO64NDB1			
G1	GFB1/IO146PDB3			
G2	GFA0/IO145NDB3			
G3	GFA2/IO144PPB3			
G4	VCOMPLF			
G5	GFC0/IO147NDB3			
G6	VCC			
G7	GND			
G8	GND			
G9	VCC			
G10	GCC0/IO67NDB1			
G11	GCB1/IO68PDB1			
G12	GCA0/IO69NDB1			
G13	IO72NDB1			
G14	GCC2/IO72PDB1			
H1	GFB0/IO146NDB3			
H2	GFA1/IO145PDB3			
НЗ	VCCPLF			
H4	GFB2/IO143PPB3			
H5	GFC1/IO147PDB3			
H6	VCC			
H7	GND			
H8	GND			
H9	VCC			

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CS281



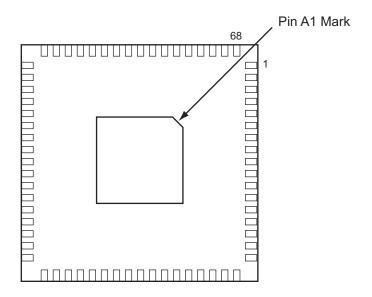
Note: This is the bottom view of the package.

Note

For more information on package drawings, see PD3068: Package Mechanical Drawings.

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QN68



Notes:

- 1. This is the bottom view of the package.
- 2. The die attach paddle center of the package is tied to ground (GND).

Note

For more information on package drawings, see PD3068: Package Mechanical Drawings.



QN132			
Pin Number	AGL250 Function		
C17	IO74RSB2		
C18	VCCIB2		
C19	TCK		
C20	VMV2		
C21	VPUMP		
C22	VJTAG		
C23	VCCIB1		
C24	IO53NSB1		
C25	IO51NPB1		
C26	GCA1/IO50PPB1		
C27	GCC0/IO48NDB1		
C28	VCCIB1		
C29	IO42NDB1		
C30	GNDQ		
C31	GBA1/IO40RSB0		
C32	GBB0/IO37RSB0		
C33	VCC		
C34	IO24RSB0		
C35	IO19RSB0		
C36	IO16RSB0		
C37	IO10RSB0		
C38	VCCIB0		
C39	GAB1/IO03RSB0		
C40	VMV0		
D1	GND		
D2	GND		
D3	GND		
D4	GND		

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IGLOO Low Power Flash FPGAs

FG144				
Pin Number	AGL125 Function			
A1	GNDQ			
A2	VMV0			
A3	GAB0/IO02RSB0			
A4	GAB1/IO03RSB0			
A5	IO11RSB0			
A6	GND			
A7	IO18RSB0			
A8	VCC			
A9	IO25RSB0			
A10	GBA0/IO39RSB0			
A11	GBA1/IO40RSB0			
A12	GNDQ			
B1	GAB2/IO69RSB1			
B2	GND			
В3	GAA0/IO00RSB0			
B4	GAA1/IO01RSB0			
B5	IO08RSB0			
B6	IO14RSB0			
B7	IO19RSB0			
B8	IO22RSB0			
B9	GBB0/IO37RSB0			
B10	GBB1/IO38RSB0			
B11	GND			
B12	VMV0			
C1	IO132RSB1			
C2	GFA2/IO120RSB1			
C3	GAC2/IO131RSB1			
C4	VCC			
C5	IO10RSB0			
C6	IO12RSB0			
C7	IO21RSB0			
C8	IO24RSB0			
C9	IO27RSB0			
C10	GBA2/IO41RSB0			
C11	IO42RSB0			
C12	GBC2/IO45RSB0			

	FG144
Pin Number	AGL125 Function
D1	IO128RSB1
D2	IO129RSB1
D3	IO130RSB1
D4	GAA2/IO67RSB1
D5	GAC0/IO04RSB0
D6	GAC1/IO05RSB0
D7	GBC0/IO35RSB0
D8	GBC1/IO36RSB0
D9	GBB2/IO43RSB0
D10	IO28RSB0
D11	IO44RSB0
D12	GCB1/IO53RSB0
E1	VCC
E2	GFC0/IO125RSB1
E3	GFC1/IO126RSB1
E4	VCCIB1
E5	IO68RSB1
E6	VCCIB0
E7	VCCIB0
E8	GCC1/IO51RSB0
E9	VCCIB0
E10	VCC
E11	GCA0/IO56RSB0
E12	IO46RSB0
F1	GFB0/IO123RSB1
F2	VCOMPLF
F3	GFB1/IO124RSB1
F4	IO127RSB1
F5	GND
F6	GND
F7	GND
F8	GCC0/IO52RSB0
F9	GCB0/IO54RSB0
F10	GND
F11	GCA1/IO55RSB0
F12	GCA2/IO57RSB0

FG144				
Pin Number	AGL125 Function			
G1	GFA1/IO121RSB1			
G2	GND			
G3	VCCPLF			
G4	GFA0/IO122RSB1			
G5	GND			
G6	GND			
G7	GND			
G8	GDC1/IO61RSB0			
G9	IO48RSB0			
G10	GCC2/IO59RSB0			
G11	IO47RSB0			
G12	GCB2/IO58RSB0			
H1	VCC			
H2	GFB2/IO119RSB1			
H3	GFC2/IO118RSB1			
H4	GEC1/IO112RSB1			
H5	VCC			
H6	IO50RSB0			
H7	IO60RSB0			
H8	GDB2/IO71RSB1			
H9	GDC0/IO62RSB0			
H10	VCCIB0			
H11	IO49RSB0			
H12	VCC			
J1	GEB1/IO110RSB1			
J2	IO115RSB1			
J3	VCCIB1			
J4	GEC0/IO111RSB1			
J5	IO116RSB1			
J6	IO117RSB1			
J7	VCC			
J8	TCK			
J9	GDA2/IO70RSB1			
J10	TDO			
J11	GDA1/IO65RSB0			
J12	GDB1/IO63RSB0			



FG144	
Pin Number	AGL600 Function
K1	GEB0/IO145NDB3
K2	GEA1/IO144PDB3
K3	GEA0/IO144NDB3
K4	GEA2/IO143RSB2
K5	IO119RSB2
K6	IO111RSB2
K7	GND
K8	IO94RSB2
K9	GDC2/IO91RSB2
K10	GND
K11	GDA0/IO88NDB1
K12	GDB0/IO87NDB1
L1	GND
L2	VMV3
L3	FF/GEB2/IO142RSB2
L4	IO136RSB2
L5	VCCIB2
L6	IO115RSB2
L7	IO103RSB2
L8	IO97RSB2
L9	TMS
L10	VJTAG
L11	VMV2
L12	TRST
M1	GNDQ
M2	GEC2/IO141RSB2
M3	IO138RSB2
M4	IO123RSB2
M5	IO126RSB2
M6	IO134RSB2
M7	IO108RSB2
M8	IO99RSB2
M9	TDI
M10	VCCIB2
M11	VPUMP
M12	GNDQ

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FG484	
Pin Number	AGL400 Function
V15	IO85RSB2
V16	GDB2/IO81RSB2
V17	TDI
V18	NC
V19	TDO
V20	GND
V21	NC
V22	NC
W1	NC
W2	NC
W3	NC
W4	GND
W5	IO126RSB2
W6	FF/GEB2/IO133RSB2
W7	IO124RSB2
W8	IO116RSB2
W9	IO113RSB2
W10	IO107RSB2
W11	IO105RSB2
W12	IO102RSB2
W13	IO97RSB2
W14	IO92RSB2
W15	GDC2/IO82RSB2
W16	IO86RSB2
W17	GDA2/IO80RSB2
W18	TMS
W19	GND
W20	NC
W21	NC
W22	NC
Y1	VCCIB3
Y2	NC
Y3	NC
Y4	NC
Y5	GND
Y6	NC

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IGLOO Low Power Flash FPGAs

FG484	
Pin Number	AGL600 Function
A1	GND
A2	GND
A3	VCCIB0
A4	NC
A5	NC
A6	IO09RSB0
A7	IO15RSB0
A8	NC
A9	NC
A10	IO22RSB0
A11	IO23RSB0
A12	IO29RSB0
A13	IO35RSB0
A14	NC
A15	NC
A16	IO46RSB0
A17	IO48RSB0
A18	NC
A19	NC
A20	VCCIB0
A21	GND
A22	GND
AA1	GND
AA2	VCCIB3
AA3	NC
AA4	NC
AA5	NC
AA6	IO135RSB2
AA7	IO133RSB2
AA8	NC
AA9	NC
AA10	NC
AA11	NC
AA12	NC
AA13	NC
AA14	NC

FG484	
Pin Number	AGL600 Function
AA15	NC
AA16	IO101RSB2
AA17	NC
AA18	NC
AA19	NC
AA20	NC
AA21	VCCIB1
AA22	GND
AB1	GND
AB2	GND
AB3	VCCIB2
AB4	NC
AB5	NC
AB6	IO130RSB2
AB7	IO128RSB2
AB8	IO122RSB2
AB9	IO116RSB2
AB10	NC
AB11	NC
AB12	IO113RSB2
AB13	IO112RSB2
AB14	NC
AB15	NC
AB16	IO100RSB2
AB17	IO95RSB2
AB18	NC
AB19	NC
AB20	VCCIB2
AB21	GND
AB22	GND
B1	GND
B2	VCCIB3
В3	NC
B4	NC
B5	NC
В6	IO08RSB0

FG484	
Pin Number AGL600 Function	
B7	IO12RSB0
B8	NC NC
B9	NC
B10	IO17RSB0
B11	NC NC
B12	NC
B13	IO36RSB0
B14	NC
B15	NC
B16	IO47RSB0
B17	IO47RSB0
B18	NC
B19	NC
B20	NC
B21	VCCIB1
B21	GND
C1	VCCIB3
C2	NC
C3	NC
C3	NC
C5	GND
C6	NC
C7	NC
C8	VCC
C9	VCC
C10	NC
C10	NC NC
C12	NC NC
C13	NC VCC
C14	VCC
C15	VCC
C16	NC
C17	NC ON E
C18	GND
C19	NC
C20	NC

FG484	
Pin Number	AGL600 Function
G5	IO171PDB3
G6	GAC2/IO172PDB3
G7	IO06RSB0
G8	GNDQ
G9	IO10RSB0
G10	IO19RSB0
G11	IO26RSB0
G12	IO30RSB0
G13	IO40RSB0
G14	IO45RSB0
G15	GNDQ
G16	IO50RSB0
G17	GBB2/IO61PPB1
G18	IO53RSB0
G19	IO63NDB1
G20	NC
G21	NC
G22	NC
H1	NC
H2	NC
H3	VCC
H4	IO166PDB3
H5	IO167NPB3
H6	IO172NDB3
H7	IO169NDB3
H8	VMV0
H9	VCCIB0
H10	VCCIB0
H11	IO25RSB0
H12	IO31RSB0
H13	VCCIB0
H14	VCCIB0
H15	VMV1
H16	GBC2/IO62PDB1
H17	IO67PPB1
H18	IO64PPB1

FG484	
Pin Number	AGL1000 Function
R9	VCCIB2
R10	VCCIB2
R11	IO147RSB2
R12	IO136RSB2
R13	VCCIB2
R14	VCCIB2
R15	VMV2
R16	IO110NDB1
R17	GDB1/IO112PPB1
R18	GDC1/IO111PDB1
R19	IO107NDB1
R20	VCC
R21	IO104NDB1
R22	IO105PDB1
T1	IO198PDB3
T2	IO198NDB3
Т3	NC
T4	IO194PPB3
T5	IO192PPB3
T6	GEC1/IO190PPB3
T7	IO192NPB3
Т8	GNDQ
Т9	GEA2/IO187RSB2
T10	IO161RSB2
T11	IO155RSB2
T12	IO141RSB2
T13	IO129RSB2
T14	IO124RSB2
T15	GNDQ
T16	IO110PDB1
T17	VJTAG
T18	GDC0/IO111NDB1
T19	GDA1/IO113PDB1
T20	NC
T21	IO108PDB1
T22	IO105NDB1

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